

# Material Declaration

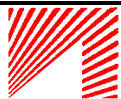


Package Type	Plastic
Package Size	14 x 9.8 mm
Terminal Finish	Matte Tin
Finish Thickness	8 microns
Weight (mg)	1050
MSL	2

Series	CPP-D-Plastic
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Item	Material	Element	Content (mg)	Content (wt%)	CAS #	
Cover	Kovar	Nickel (Ni)	0.658	0.063%	7440-02-0	
		Cobalt (Co)	0.383	0.036%	7440-48-4	
		Iron (Fe)	1.230	0.117%	7439-89-6	
Base	Ceramic	Alumina (Al <sub>2</sub> O <sub>3</sub> )	8.395	0.800%	1344-28-1	
		Silicon Dioxide (SiO <sub>2</sub> )	0.334	0.032%	14808-60-7	
		Chromium Oxide (Cr <sub>2</sub> O <sub>3</sub> )	0.358	0.034%	1308-38-9	
		Titanium Oxide (TiO <sub>2</sub> )	0.093	0.009%	13463-67-7	
		Calcium Oxide (CaO)	0.032	0.003%	1305-79-9	
		Magnesium Oxide (MgO)	0.046	0.004%	1309-48-4	
		Tungsten (W)	1.273	0.121%	7440-33-7	
	Seal Ring		Nickel (Ni)	0.497	0.047%	7440-02-0
			Gold (Au)	0.057	0.005%	7440-57-5
			Iron (Fe)	0.621	0.059%	7439-89-6
			Cobalt (Co)	0.236	0.023%	7440-48-4
	Silver Solder		Silver (Ag)	0.182	0.017%	7440-22-4
			Copper (Cu)	0.032	0.003%	7440-50-8
Leadframe		Copper (Cu)	47.422	4.516%	7440-50-8	
		Tin (Sn)	0.829	0.079%	7440-31-5	
		Zinc (Zn)	0.007	0.001%	7440-66-6	
		Iron (Fe)	0.007	0.001%	7439-89-6	
		Phosphorus (P)	1.117	0.106%	7723-14-0	
		Tin (Sn)	0.171	0.016%	7440-31-5	
IC	IC	Aluminum (Al)	0.001	0.000%	7429-90-5	
		Titanium (Ti)	0.000	0.000%	7440-32-6	
		Silicon (Si)	0.338	0.032%	7440-21-3	
	Gold	Gold (Au)	0.101	0.010%	7440-57-5	
	Adhesive	Silver (Ag)	0.000	0.000%	7440-22-4	
Epoxy		0.000	0.000%			
Capacitor	Body	Nickel (Ni)	0.010	0.001%	7440-02-0	
		BaTiO <sub>3</sub>	0.816	0.078%	12047-27-7	
	Termination	Nickel (Ni)	0.013	0.001%	7440-02-0	
		Tin (Sn)	0.019	0.002%	7440-31-5	
		Copper (Cu)	0.025	0.002%	7440-50-8	
Crystal	Crystal	Silicon Dioxide (SiO <sub>2</sub> )	0.307	0.029%	14808-60-7	

	Electrode	Silver (Ag)	0.006	0.001%	7440-22-4
		Nickel (Ni)	0.000	0.000%	7440-02-0
	Adhesive	Silver (Ag)	0.000	0.000%	7440-22-4
		Silicon (Si)	0.000	0.000%	7440-21-3
Plastic		Silicon Dioxide (SiO2)	663.073	63.150%	14464-46-1
		Epoxy Resin	128.381	12.227%	
		Aldehyde Resin	105.039	10.004%	
		Bromine (Br)	11.670	1.111%	7726-95-6
		Antimony Trioxide (Sb2O3)	11.670	1.111%	1309-64-4
Circuit Board	FR-4	Phenol, 4,4'-(1-methylethylidene)bis(2,6-dibromo-,polymer with (chloromethyl)oxirane and 4,4'-(1-methylethylidene)bis(phenol)	20.081	1.913%	26265-08-7
		Copper (Cu)	10.953	1.043%	7440-50-8
		GF-Fibre	29.818	2.840%	
	Copper Anode	Copper (Cu)	1.017	0.097%	7440-50-8
	Soldermask	Bisphenol A, epichlorohydrin polymer	0.169	0.016%	25068-38-6
		(2-Methoxymethylethoxy)propanol	0.042	0.004%	34590-94-8
		Barium sulphate	0.148	0.014%	7727-43-7
		2-Methyl-1-(4-methylthiophenyl)-2-morpholinopropan-1-one	0.042	0.004%	71868-10-5
		Dipropylene glycol ethyl ether	0.021	0.002%	15764-24-6
	ENIG	Nickel bis(sulphamidate)	0.137	0.013%	13770-89-3
	Gold (Au)	0.004	0.000%	7440-57-5	
High Temperature	RoHS exemption 7(a)	Lead (Pb)	1.906	0.182%	7439-92-1
		Tin (Sn)	0.212	0.020%	7440-31-5
<b>Total</b>			<b>1050.000</b>	<b>100.000%</b>	



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